

Option 1: Qubits in Gate-Defined Silicon Quantum Dots UW/Delft/Harvard/SNL Collaboration

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Program Review, Jan. 27th, 2020

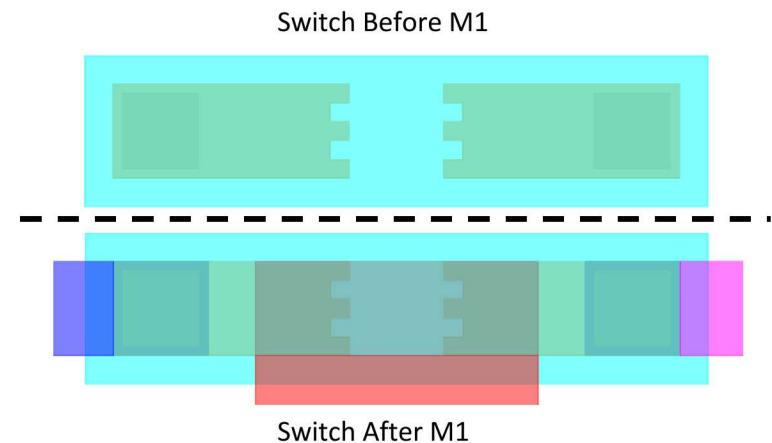
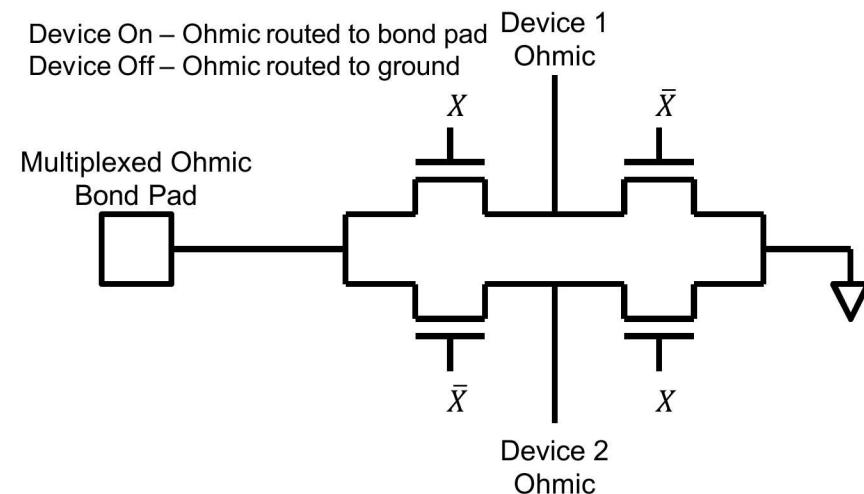
SNL Tasks

1. Charge noise measurement platform
 - Comparison of Hall and charge noise for different cap thicknesses and dielectric films
 - Resolving aluminum gate issues
2. Octuple quantum dot fabrication
 - Towards 4 qubit project goal
 - Gate design from Wisconsin
 - RF PCB Design included in work

Charge Noise Platform

- Goal: Multiple (32) charge noise measurements on a single die to assess variability
- Approach: Implement on-chip multiplexing to enable measuring 16 different double QD systems (double QD = 2x charge noise measurements)
 - Verify multiplexing operation with Hall bars
 - Decreases yield requirements
 - Mobility across die is also interesting
 - Devices delivered at end of CY19
 - Double QD systems ready for nanostructures
 - Resolving aluminum gate issues
 - Aluminum gate issues must be resolved for 8-QD devices as well
 - Expect to deliver in March

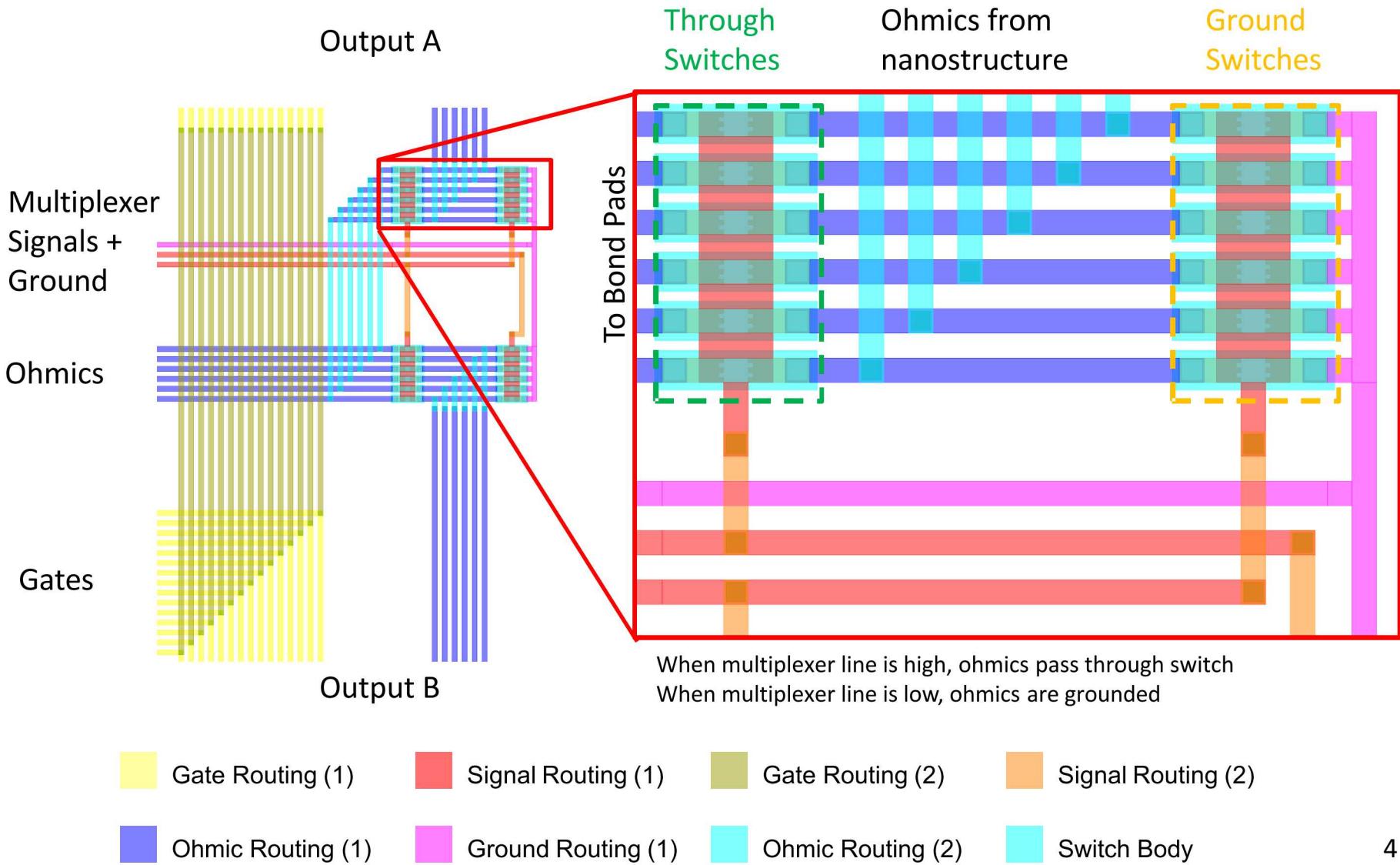
- Device On – Ohmic routed to bond pad
- Device Off – Ohmic routed to ground



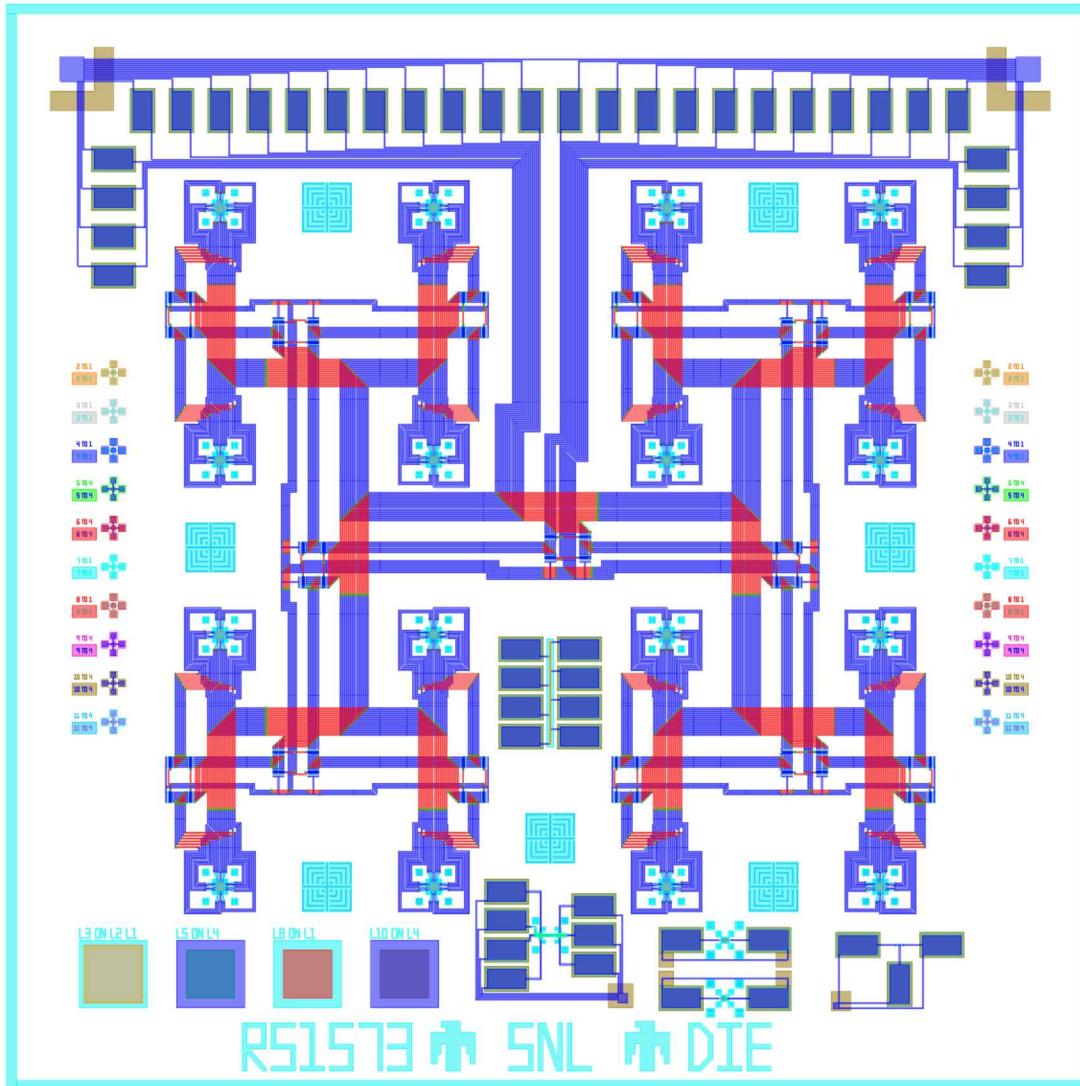
Legend for the 3D model:

- Ohmic Routing (1) (Blue)
- Implant (Green)
- Implant Via (Light Green)
- Signal Routing (1) (Red)
- Ground Routing (1) (Magenta)
- Switch Body (Cyan)

Multiplexer routing

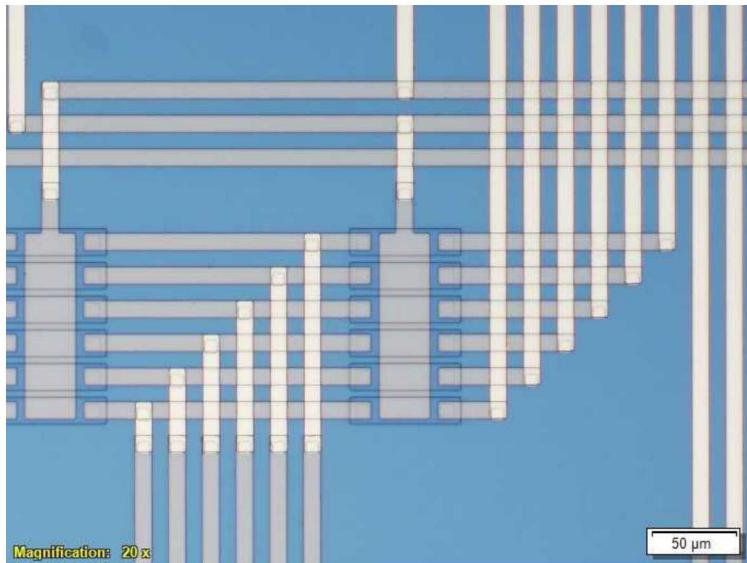


Full design

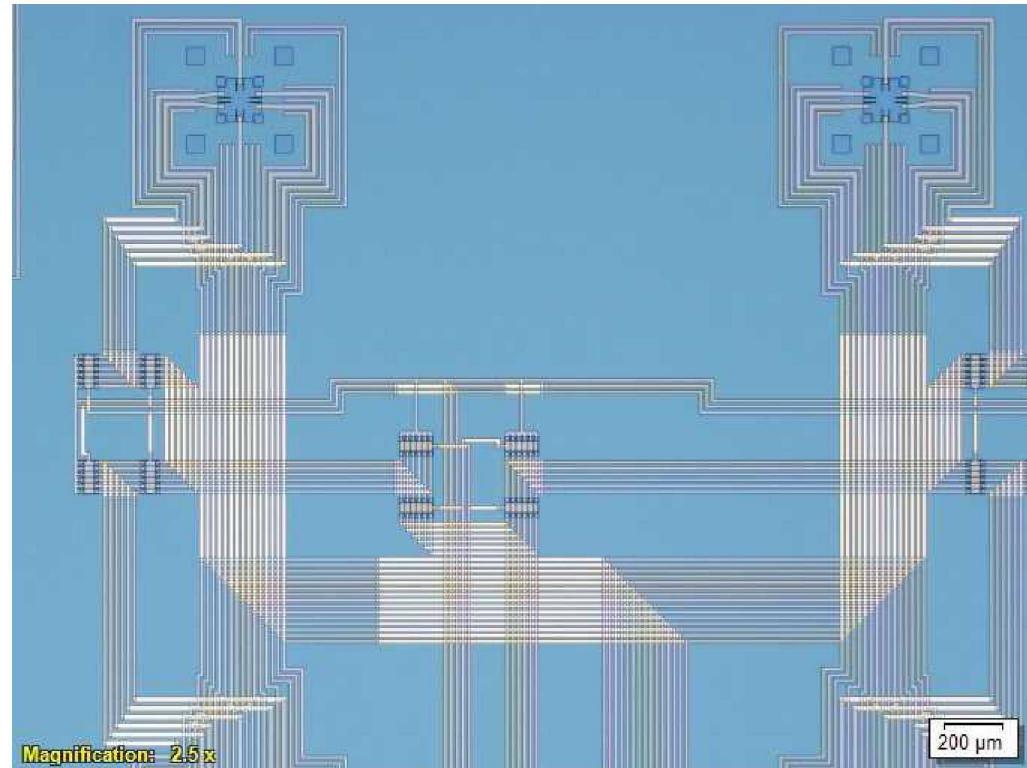


- 10x10 mm die
- 16 DQD devices
- 11 mask levels + EBL
- 2 metal routing layers (blue,red)
- 360 routing switches
- Diagnostics
 - Ohmic conduction
 - Gate isolation
 - Hall
 - Switch isolation

Fabrication in process

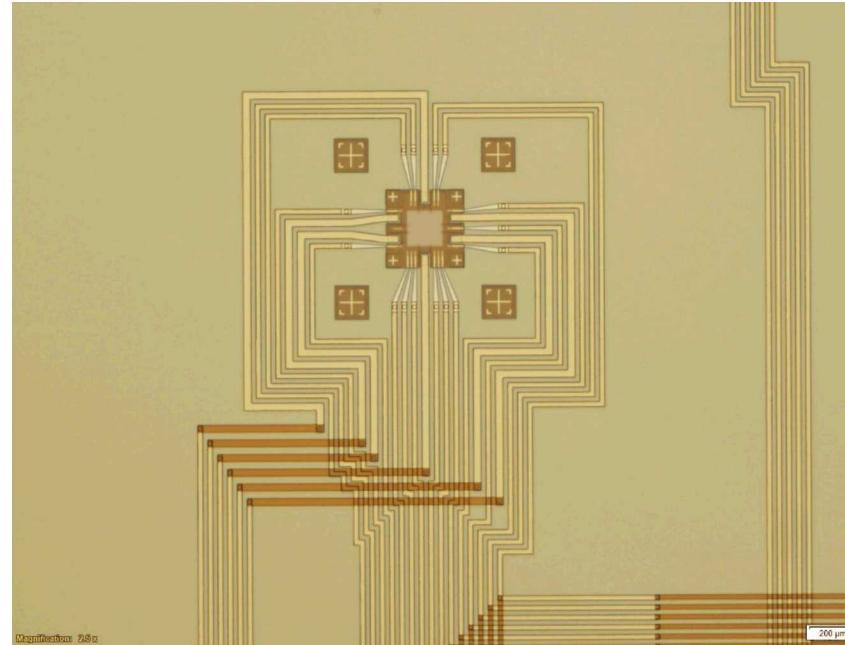


Switch Block after M2



Construction zones after M2

Completed die without nanostructure

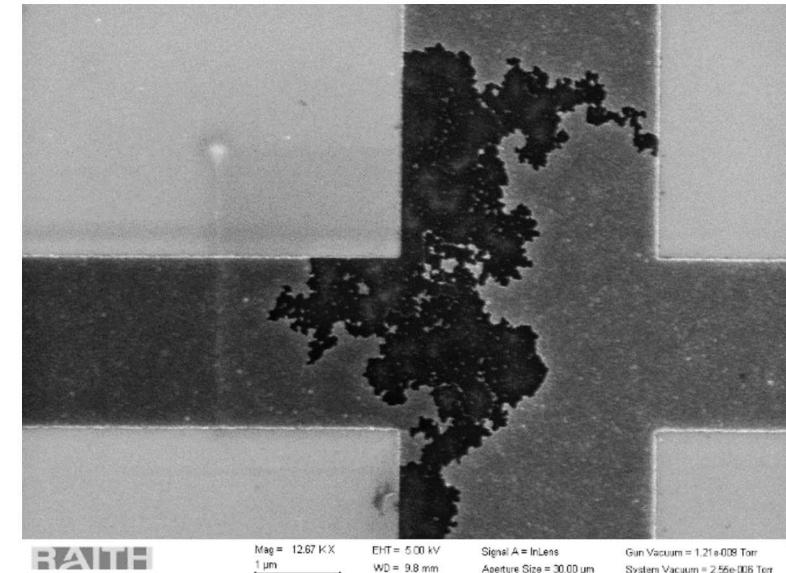
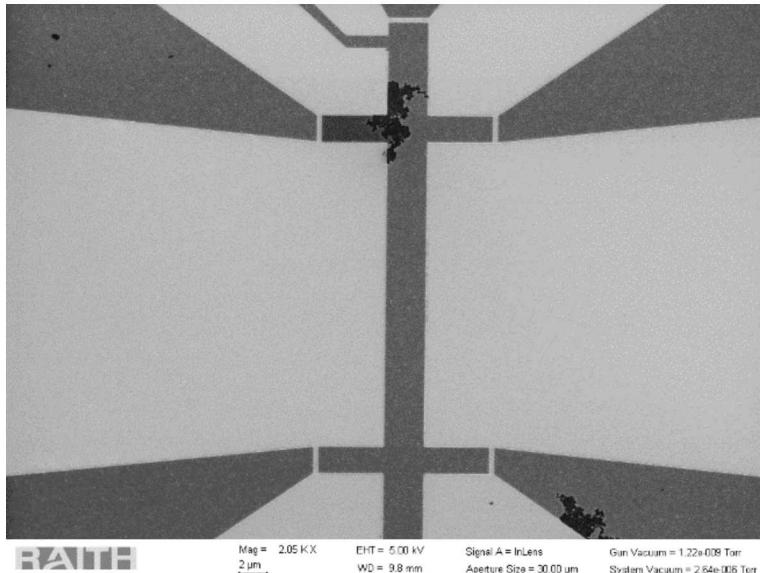


Next steps

- Add nanostructures
 - Validate switch performance - UW
 - Fabricate with DQD
 - Improve yield by changing number of devices patterned per die
 - Working aluminum gate issue

Aluminum gate issue

- Random patches of aluminum in gates is fully oxidizing
- Suspicion is that background pressure of oxygen is causing issues
- Tentative solution: Titanium gettering evaporation + high growth rate Aluminum deposition at -180C
 - Initial testers complete



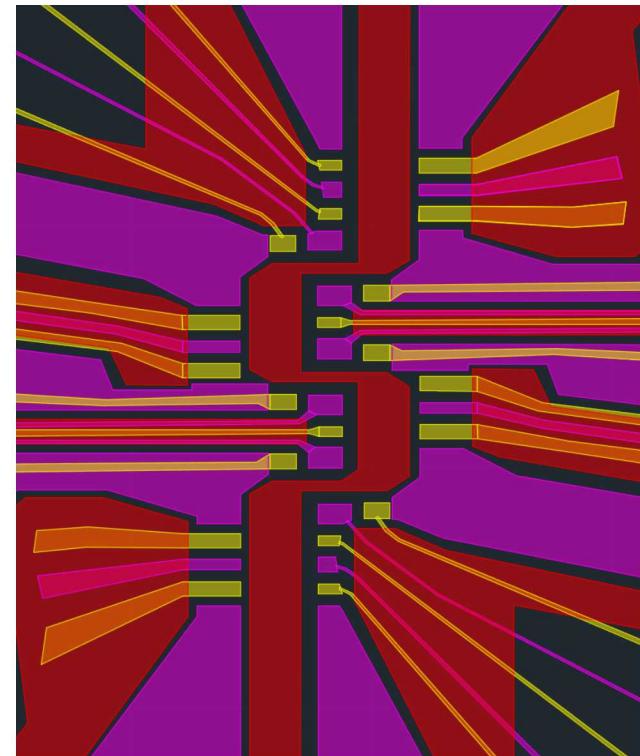
Example of aluminum oxidation issue

Octuple Quantum Dots

- Goal: Build devices with 8QDs with consideration for minimizing RF cross talk
- Approach:
 - UW nanostructure design
 - RF wave guiding on chip (SNL design)
 - Developing PCB design tailored to chip layout

8 dot devices

- Squiggle dot design from UW
- 4 capacitively coupled double QDs with opposing charge sensors
- SNL is designing die and PCB compatible with design



Cartoon Schematic of 8 dot device

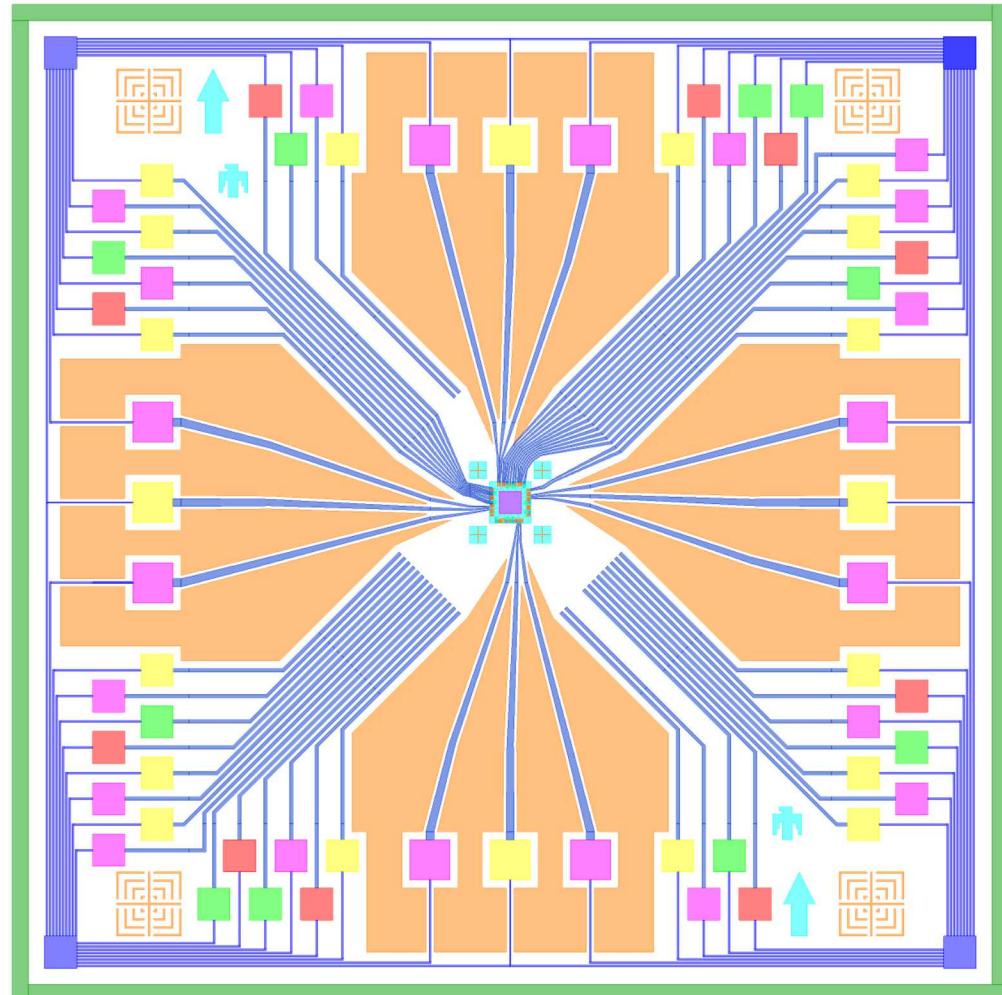
 Isolation

 Accumulation

 Tunnel barrier

8 dot device

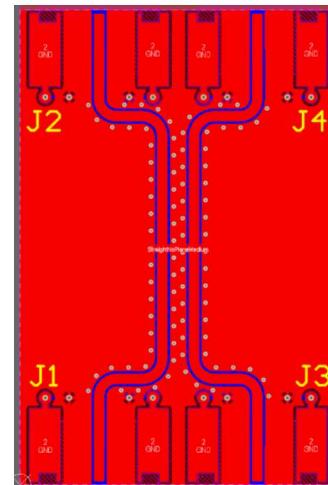
- 52 gates (yellow, magenta, red)
- 12 waveguided gates (orange ground plane)
- 10 ohmics (green)
- In progress
 - Multiple iterations with UW
 - Compatibility across fabs
 - Incorporate up to the minute learning
 - Test fabrication run nearly complete
- Delivery
 - May timeframe



PCB Work

- What level of PCB complexity is needed?
- Built PCBs with and without extra ground planes (adjusting waveguides as needed)
- Experimentally no improvement in crosstalk using more complicated ground plane scheme
- Will test at 4K
- Informing 8QD PCB design

Single ground plane



Extra ground plane

